

Manufacturer:

Chipset Maker:

Manufacturer P/N:

CRYSTAL SPECIFICATION

ECS Inc. International

ECS-480-CDX-2451

ST Micro

Chipset:	STM32WL33
Customer Approval :	

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Sales: sales@ecsxtal.com
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Date: 02-07-2024

Approved By: B. Slatten

Checked By: D. Kelly

Designer: A. Anderson

Address: 15351 W. 109th Street Lenexa Kansas 66219



Rev.	Description of Revision History	Date	Designer	Checked By
1	New Publication	02-07-2024	A. Anderson	By D. Kelly



CRYSTAL SPECIFICATION

1. Description : Quartz Crystal

2. Nominal Frequency : 48.000000 MHz

3. Center Frequency : 48.000000 MHz

4. Dimension & Drawing No. : ECX-1247

5. Oscillation Mode : Fundamental

6. Cutting Mode : AT cut

7. Packing Style : Tape & Reel

8. Measurement Instrument : S&A 250B(Measured FL)

9. Electrical Characteristics :

[1] Operating Conditions:

Item	Symbol	MIN.	TYP.	MAX.	Unit	Condition
Operating Temperature Range	Topt	-40		105	°C	
Storage Temperature Range	Tstg	-40		105	°C	
Load Capacitance	CL		8		pF	
Drive Level	DL			200	μW	

[2] Frequency Stability:

Item	Symbol	MIN.	TYP.	MAX.	Unit	Condition
Tolerance	dF/Fo	-10		10	ppm	Refer to Center Frequency @25±3°C
Stability Over Temperature	dF/F25	-25		25	ppm	-40 ~ +105°C
Aging	dF/F25	-5		5	ppm	5 Years

dF/Fo: Frequency Deviation Refer to Center Frequency dF/F25: Frequency Deviation Refer to 25 °C Frequency



[3] Electrical Performance:

Item	Symbol	MIN.	TYP.	MAX.	Unit	Condition
Equivalent Series Resistance	ESR			80	Ω	@Series
Shunt Capacitance	C0			5	pF	
Insulation Resistance	IR	500			ΜΩ	@DC 100 Volt

10. Marking: Laser

E480Y
2451

* "Y" in the part marking denotes a variable ECS internal lot.

11. Remark:

*Compliant with EU RoHS 2015/863		
* MSL 1		

■Note

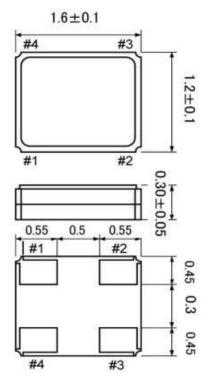
1. General cleaning solutions or ultrasonic cleaning method may be used to clean our products. However, under certain circumstances, ultrasonic cleaning machines could generate resonance at the oscillation frequency of our products and thus deteriorate the electrical characteristics in devices, and even damage the overall structure of devices. Therefore, verification test is recommended before cleaning.

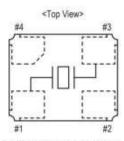
2. Avoid mounting and processing by Ultrasonic welding this method has a possibility of an excessive vibration spreading inside the crystal products and becoming the cause of characteristic deterioration and not oscillating.



Dimensions: Top, Side and Bottom View

Unit: mm

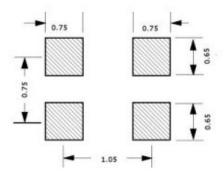




<#2 & #4 : Grounded to metal lid>

Pad Connections		
1	In/Out	
2	Gnd	
3	Out/In	
4	Gnd	

Land Pattern: (Reference)





RELIABILITY SPECIFICATION

1. ENVIRONMENTAL PERFORMANCE

ITEM	CONDITION					
1. HIGH TEMPERATURE	STORED AT 85±2°C FOR 1000±12H. (If Customer's temperature request is					
STORAGE	higher than the standard, Temperature test must be done for customer					
	requirements.)	requirements.)				
	THEN 25±2°C OVER 2H I	BEFORE TESTING.				
2. LOW TEMPERATURE	STORED AT -40±2°C FO	R 500±12H. (If Customer's temperature request is				
STORAGE		mperature test must be done for customer				
	requirements.)					
	THEN 25±2°C OVER 2H I	BEFORE TESTING.				
3. HIGH TEMP. & HUMIDITY	STORED AT 60 ± 2 °C AND HUMIDITY $90 \sim 95\%$ FOR 500 ± 12 H.					
	THEN 25±2°C OVER 2H I	BEFORE TESTING.				
4. TEMPERATURE CYCLE	THE CRYSTAL UNIT SH	ALL BE SUBJECTED TO 1000 SUCCESSIVE				
	CHANGE OF TEMPERAT	FURE CYCLES, THEN 25 \pm 2°C OVER 2 H				
	BEFORE TESTING, EAC	H CYCLE AS BELLOW:				
	TEMPERATURE	DURATION				
	140+0/-6°C	$30 \pm 3 \text{MINUTES}$				
	2. 25°C ± 2°C	2~3 MINUTES				
	3. 125+4/-0°C	30 ±3 MINUTES				
	4. 25°C ± 2°C	2∼3 MINUTES				

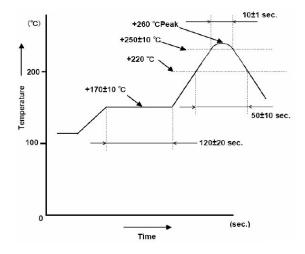
2. MECHANICAL PERFORMANCE

ITEL (CONDITION
ITEM	CONDITION
5. SOLDERABILITY	THE LEAD IS IMMERSED IN A $260 \pm 5^{\circ}$ C SOLDER BATH WITHIN
	2±0.6 SECONDS.
6. RESISTANCE TO	REFLOW CHART AS ATTACH SHEET. TWICE PASS.
SOLDERING HEAT	
7. FREE FALL	FREE DROPPING FROM 75 cm HEIGHT 3 TIMES ON A HARD
	WOODEN BOARD.
8. VIBRATION	FREQUENCY: 10~55Hz,
	AMPLITUDE (TOTAL EXCURSION) : $1.5 \text{mm} \pm 15\%$,
	SWEEP TIME: 1MIN, 3 DIRECTION(X, Y, Z) EACH FOR 2 Hrs.
9. GROSS LEAK	STANDARD SAMPLE FOR AUTOMATIC GROSS LEAK DETECTOR,
	TEST PRESSURE: 0.2 Mpa
10. FINE LEAK	HELIUM BOMBING 5.0~5.5 Kgf / cm ²
	FOR 2 HOURS.



11. TERMINAL STRENGTH	SHALL BE PRESSURIZED AT A SPEED OF APPROX.0.5mm/sec IN THE DIRECTION INDICATED BY THE ARROW UNTIL THE BENDING WIDTH REACHES 3mm AND HELD FOR 5 SECONDS.
12. STICKING TENDENCY	A R0.5 JIG SHALL BE USED TO APPLY A 10N DEAD LOAD IN THE DIRECTION INDICATED BY THE ARROW TO THE ELEMENT AND RETAIN IT FOR 10 SECONDS.
13. ELEMENT ASSEMBLY	A R0.5 PRESSURIZED BAR SHALL BE USED TO APPLY A 10N
STRENGTH	LOAD IN THE CENTER OF ELEMENT AND RETAIN IT FOR 10
	SECONDS.

◆ SUGGESTED REFLOW PROFILE





◆ PACKING Unit: mm

1. CARRIER TYPE

